

DB3S406F

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Small reverse current I_R
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Repetitive peak reverse voltage	V_{RRM}	40	V
Forward current	Single	100	mA
	Series *1	75	
Peak forward current	Single	300	mA
	Series *1	225	
Non-repetitive peak forward surge current *2	Single	1	A
	Series *1	0.75	
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: Value of each diode in series diodes used.

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

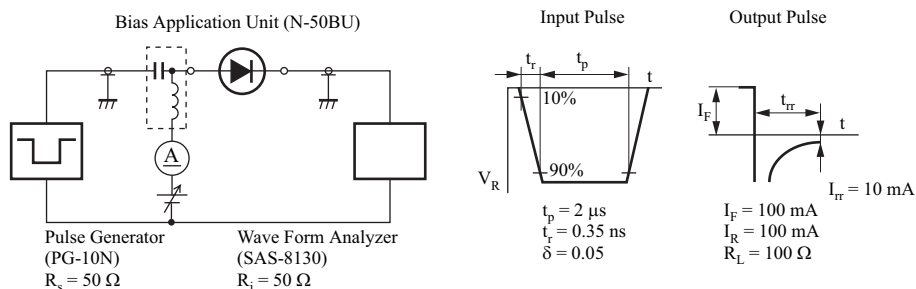
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100 \text{ mA}$			0.6	V
Reverse current	I_R	$V_R = 40 \text{ V}$			5	μA
Terminal capacitance	C_t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		2.2		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		0.9		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz

*: t_{rr} measurement circuit



■ Package

• Code

SSMini3-F3-B

• Pin Name

1: Anode-1

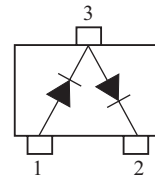
3: Cathode-1

2: Cathode-2

Anode-2

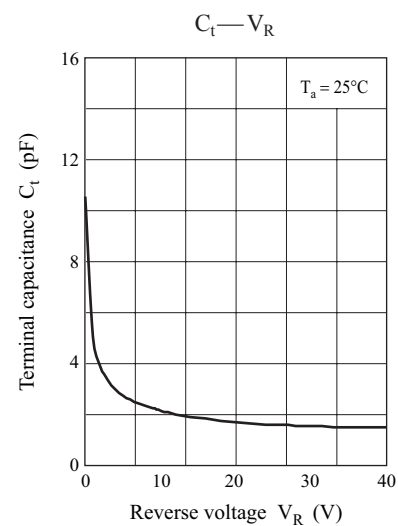
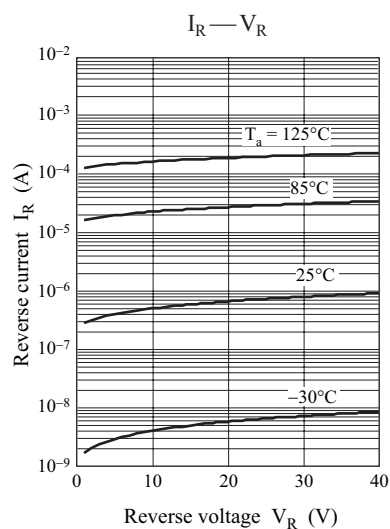
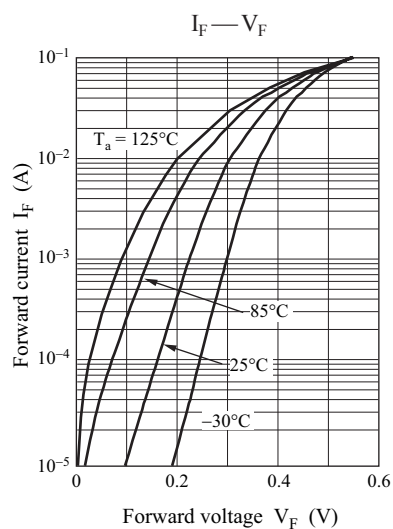
■ Marking Symbol: 4V

■ Internal Connection



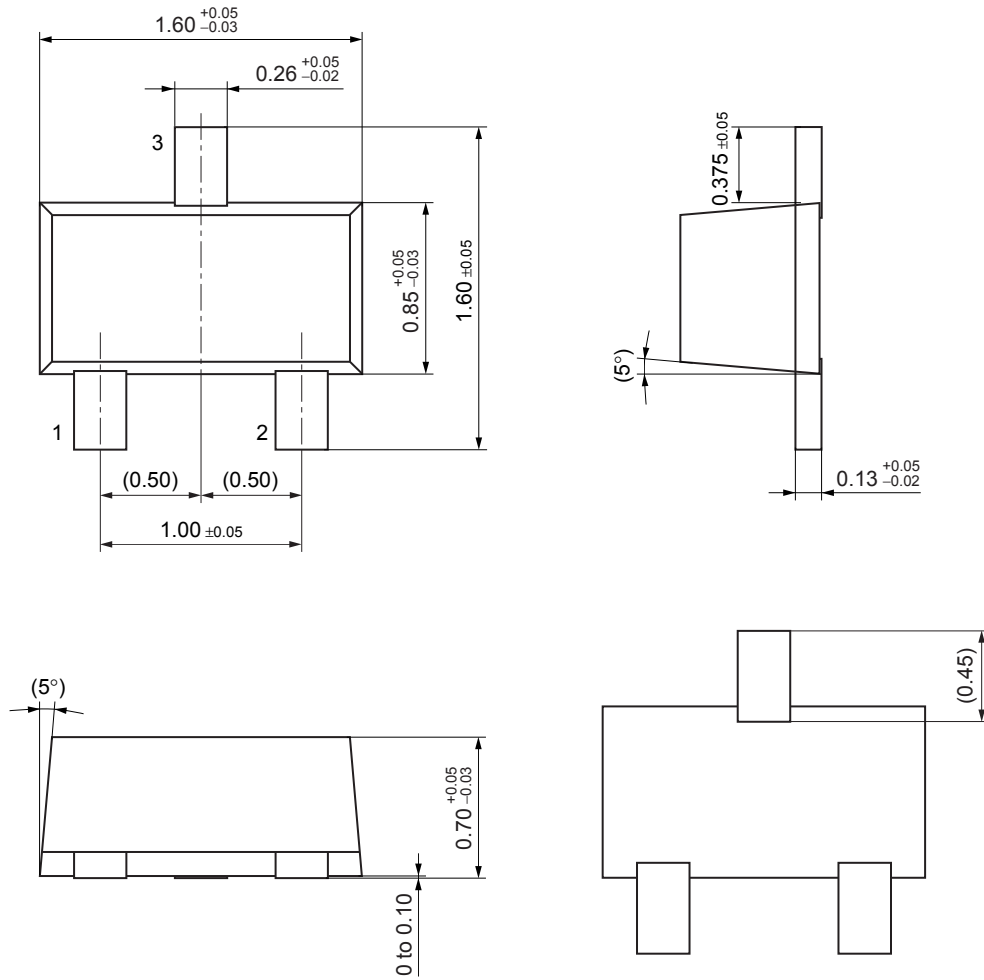
DB3S406F

Panasonic



SSMini3-F3-B

Unit: mm



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